

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Weng Hong TEH</td> <td>01/18/2012</td> </tr> <tr> <td>Robert Bob. L. SANKMAN</td> <td>01/18/2012</td> </tr> </tbody> </table>		Name	Execution Date	Weng Hong TEH	01/18/2012	Robert Bob. L. SANKMAN	01/18/2012
Name	Execution Date						
Weng Hong TEH	01/18/2012						
Robert Bob. L. SANKMAN	01/18/2012						
RECEIVING PARTY DATA							
Name:	INTEL CORPORATION						
Street Address:	2200 MISSION COLLEGE BOULEVARD						
Internal Address:	RNB-4-150						
City:	Santa Clara						
State/Country:	CALIFORNIA						
Postal Code:	95052						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>PCT Number:</td> <td>US2011064567</td> </tr> </tbody> </table>		Property Type	Number	PCT Number:	US2011064567		
Property Type	Number						
PCT Number:	US2011064567						
CORRESPONDENCE DATA							
Fax Number:	(408)720-8383						
Phone:	(408) 720-8300						
Email:	maki_cho@bstz.com						
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>							
Correspondent Name:	Maki Cho						
Address Line 1:	1279 OAKMEAD PARKWAY						
Address Line 4:	SUNNYVALE, CALIFORNIA 94085						
ATTORNEY DOCKET NUMBER:	42390P38760PCT						
NAME OF SUBMITTER:	Michael J. Mallie						
Total Attachments: 4 source=P38760PCT_Assignment#page1.tif source=P38760PCT_Assignment#page2.tif source=P38760PCT_Assignment#page3.tif source=P38760PCT_Assignment#page4.tif							

CH \$40.00 US2011064567

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

WENG HONG TEH; ROBERT BOB. L. SANKMAN

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the International application entitled:

THROUGH-SILICON VIA RESONATORS IN CHIP PACKAGES AND METHODS OF ASSEMBLING SAME

(I hereby authorize and request my attorney, associated with Customer Number 45209, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on December 13, 2011 as

International Application Number PCT/US2011/064567 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below.

and in and to said International application and all related applications (e.g. national phase applications, divisional applications, continuation applications, reexaminations, reissues, and the like) that have been or shall be filed in the United States and/or all foreign countries on said inventions and improvements, as well as in and to all rights of priority resulting from the filing of said International application;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said

inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Weng Hong Teh

4/18/12

(Today's Date)

Robert bob. L. Sankman

(Today's Date)

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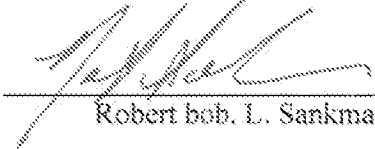
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Weng Hong Teh

(Today's Date)



Robert bob. L. Sankman

1/18/2012

(Today's Date)